Specification of Thermoelectric Module

TEC1-19912

Description

The 199 couples, 40 mm \times 40 mm size module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

Performance Specification Sheet

Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

| Th(°C) | 27 | 50 | Hot side temperature at environment: dry air, N ₂ | |
|----------------------------|-------|-------|---|--|
| DT _{max} (°C) | 70 | 79 | Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side | |
| U _{max} (Voltage) | 25.0 | 26.6 | Voltage applied to the module at DT _{max} | |
| I _{max(} amps) | 11.3 | 11.3 | DC current through the modules at DT _{max} | |
| Q _{Cmax} (Watts) | 177.3 | 191.7 | Cooling capacity at cold side of the module under DT=0 °C | |
| AC resistance(ohms) | 1.70 | 1.88 | The module resistance is tested under AC | |
| Tolerance (%) | ± 10 | | For thermal and electricity parameters | |

Geometric Characteristics Dimensions in millimeters

40.0 ± 0.3 Ŧ Positive lead wire (Red) 40.0 ± 0.3 18AWG leads, PVC insulated Negative lead wire (Black) 150 ± 3 Cold side: To See ordering option Hot side: Th 7 See ordering option //See ordering option A

Thickness

1:3.2±0.03

(mm)0:3.2±0.1

Suffix

TF

TF

Ordering Option

Standard/

Flatness/

Parallelism (mm)

0:0.05/0.08

1:0.03/0.03

Eg. TF01: Thickness 3.2 ± 0.1 (mm) and Flatness 0.03/0.03 (mm)

Manufacturing Options

| E | A. Solder: | B. Sealant: | |
|----------------|---|-----------------------------------|--|
| | 1. T100: BiSn (Tmelt=138°C) | 1. NS: No sealing (Standard) | |
| | 2. T200: CuAgSn (Tmelt = 217°C) | 2. SS: Silicone sealant | |
| | 3. T240: SbSn (Tmelt = 240°C) | 3. EPS: Epoxy sealant | |
| | C. Ceramics: | D. Ceramics Surface Options: | |
| | 1. Alumina (Al ₂ O ₃ , white 96%) | 1. Blank ceramics (not metalized) | |
| | 2. Aluminum Nitride (AlN) | 2. Metalized | |
| n | Namin | g for the Module | |
| Lead wire ler | ngth(mm) TEC1-19912- X-X | ТЕС1-19912- х-х-х-х тттт | |
| Standard/Optio | onal length | Ceramics Flatness/ Parallelism | |
| 150±3/Sp | becify | Sealant | |

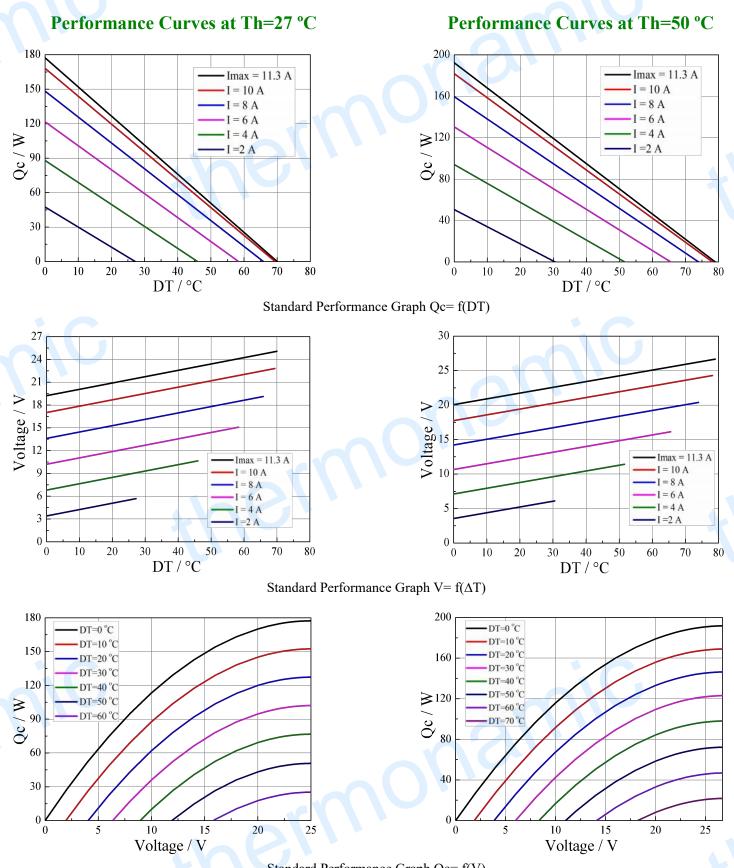
Solder TEC1-19912-T200 -NS -TF01 -AlO T200: CuSn (Tmelt=227°C) NS: No sealing AlO: Alumina white 96%

TF01: Thickness ±0.1(mm) and Flatness/Parallelism (mm): 0.025/0.025

150±3/Specify

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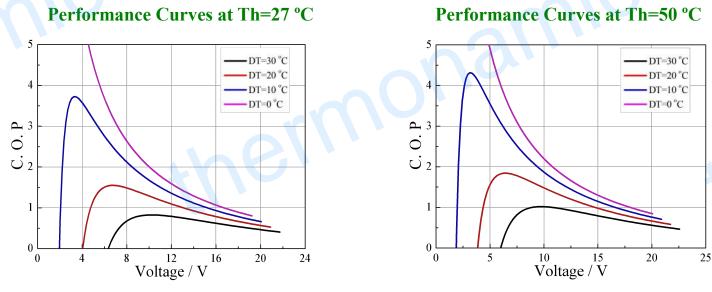
TEC1-19912



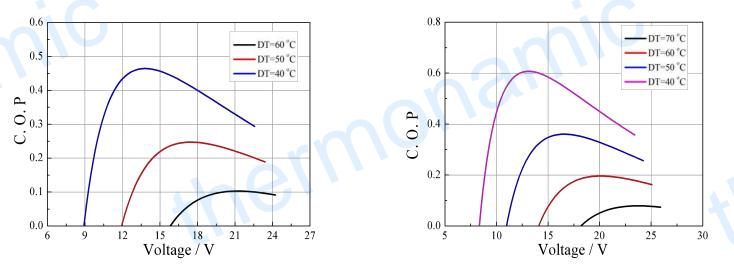
Standard Performance Graph Qc = f(V)

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Standard Performance Graph COP = f(V) of ΔT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of ΔT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating.
- Storage module below 100 °C
- \bullet Operation below I_{max} or V_{max}
- Work under DC